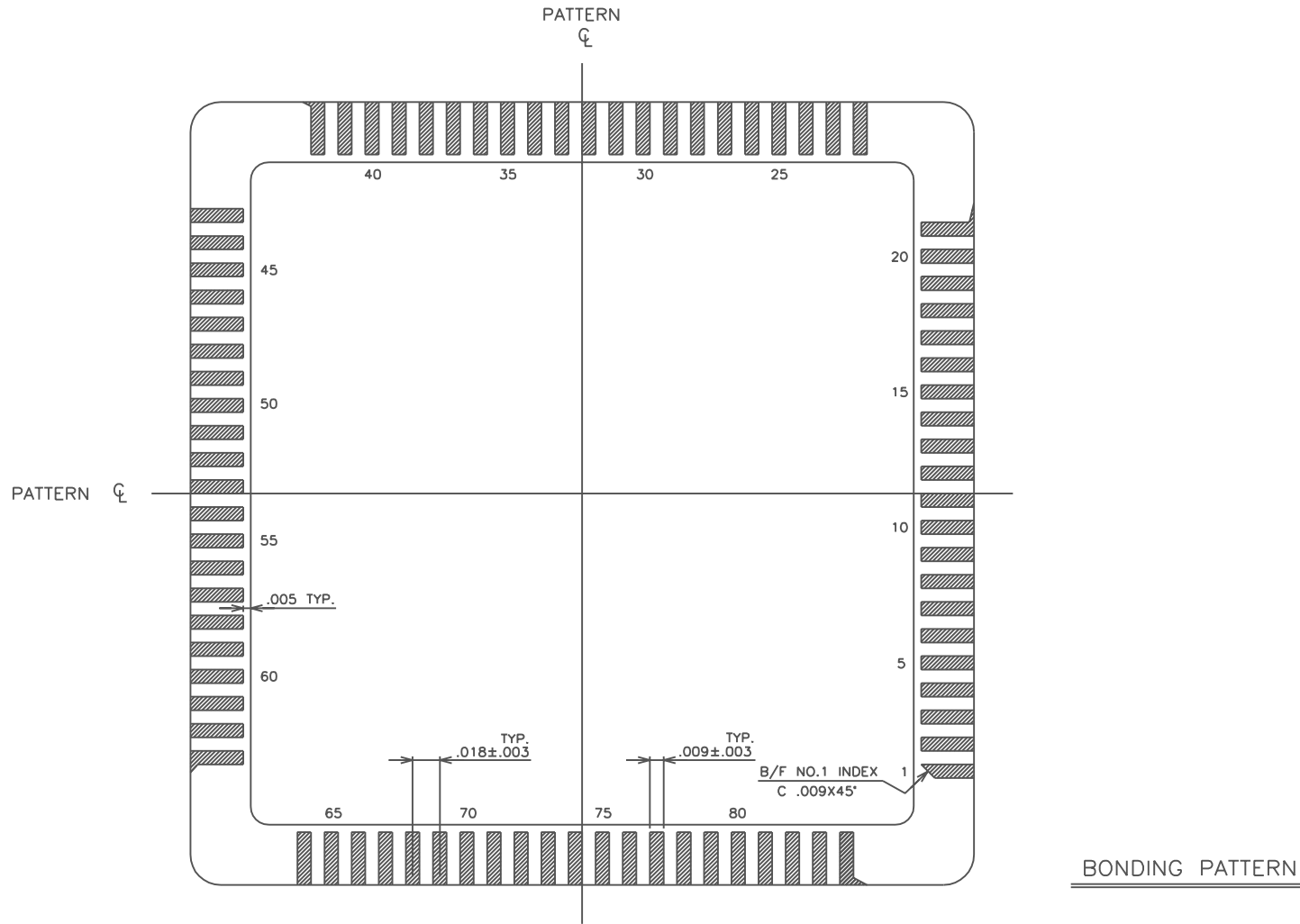


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 4. LEAD RESISTANCE:
 B/F NO.1,11,22,32,43,53,64,74 ----- 200mΩ MAX.
 THE OTHERS ----- 500mΩ MAX.

MODIFICATION						NAME	85 PIN GRID ARRAY PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED	±.005	THIRD ANGLE PROJECTION	PB085Y814-1	S=0 D=0		
						SCALE	5/1	MATERIAL	AS INDICATED			DRAWN	CHECKED	APPROVED	DATE
												M.KA	A.F	M.K	OCT.19.90
	REDRAWN:CORRECTED MATERIAL NAME	JUN21.96	X.X	S.F/K/M	T.A										
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION					DRAWING NO.			SHEET
							KYOTO JAPAN					1/3	1/3		
												1/3			





MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					85 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	M.KA	A.F	M.K	OCT.19.90
					SCALE 20/1	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
							KD-P90814-A		2/3	



WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	B2
2	C2
3	B1
4	C1
5	D2
6	D1
7	E3
8	E2
9	E1
10	F2
11	F3
12	G3
13	G1
14	G2
15	F1
16	H1
17	H2
18	J1
19	K1
20	J2


W/B NO.	PIN NO.
21	L1
22	K2
23	K3
24	L2
25	L3
26	K4
27	L4
28	J5
29	K5
30	L5
31	K6
32	J6
33	J7
34	L7
35	K7
36	L6
37	L8
38	K8
39	L9
40	L10

W/B NO.	PIN NO.
41	K9
42	L11
43	K10
44	J10
45	K11
46	J11
47	H10
48	H11
49	F10
50	G10
51	G11
52	G9
53	F9
54	F11
55	E11
56	E10
57	E9
58	D11
59	D10
60	C11

W/B NO.	PIN NO.
61	B11
62	C10
63	A11
64	B10
65	B9
66	A10
67	A9
68	B8
69	A8
70	B6
71	B7
72	A7
73	C7
74	C6
75	A6
76	A5
77	B5
78	C5
79	A4
80	B4

W/B NO.	PIN NO.
81	A3
82	A2
83	B3
84	A1

S/R	NC
D/A	NC
EXTRA PIN C3	C2

MODIFICATION						NAME 85 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K.A	CHECKED A.F	APPROVED M.K	DATE OCT.19.'90
						SCALE X	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P90814-A	SHEET 3/3		

